8-bit Proprietary Microcontroller

CMOS

F²MC-8L MB89820 Series

MB89821/823/P825/PV820

■ DESCRIPTION

MB89820 series is a line of single-chip microcontrollers using the F²MC-8L* CPU core which can operate at low voltage but at high speed. In addition to an LCD controller/driver allowing 200-pixel display the microcontrollers contain a variety of peripheral functions such as timers, a UART, a serial interface, and an external interrupt. The configuration of the MB89820 series is therefore best suited to control of LCD display panels.

*: F2MC stands for FUJITSU Flexible Microcontroller.

■ FEATURES

- Minimum execution time: 0.8 μs/5 MHz (Vcc = +5.0 V)
- F2MC-8L family CPU core

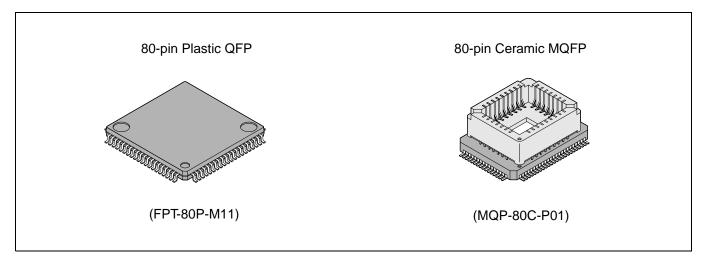
Instruction set optimized for controllers

Multiplication and division instructions 16-bit arithmetic operations Test and branch instructions Bit manipulation instructions, etc.

LCD controller/driver
 Max. 50 segments × 4 commons
 Divided resistor for LCD power supply

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■ PACKAGES



(Continued)

• Three types of timers

8-bit PWM timer (also usable as a reload timer)

8-bit pulse width count timer (also usable as a reload timer)

20-bit time-base timer

• Two serial interfaces

8-bit synchronous serial interface (Switchable transfer direction allows communication with various equipment.) UART (5-, 7-, 8-bit transfer capable)

• External interrupt: 2 channels

Capable of wake-up from low-power consumption modes (with an edge detection function)

• Low-power consumption modes

Stop mode (Oscillation stops to minimize the current consumption.)

Sleep mode (The CPU stops to reduce the current consumption to approx. 1/3 of normal.)

■ PRODUCT LINEUP

Part number Parameter	MB89821	MB89823	MB89P825	MB89PV820	
Classification		ction product // products)	One-time PROM product	Piggyback/evaluation product for evaluation and development	
ROM size	4 K × 8 bits (internal mask ROM)	8 K \times 8 bits (internal mask ROM)	16 K × 8 bits (internal PROM, programming with general-purpose EPROM programmer)	32 K × 8 bits (external ROM)	
RAM size	128 × 8 bits	256	× 8 bits	1024 × 8 bits	
CPU functions	Number of instr Instruction bit le Instruction leng Data bit length: Minimum execu Interrupt proces	ength: 8 th:	136 8 bits 1 to 3 bytes 1, 8, 16 bits 0.8 μs/5 MHz (Vcc = 5.0 V) 7.2 μs/5 MHz (Vcc = 5.0 V)		
Ports	I/O ports (N-ch I/O ports (N-ch I/O ports (CMO Input ports: Total:	open-drain): 6 S): 6	16 (All also serve as seg 5 6 (5 ports also serve as 4 (1 port also serves as interrupt input.) 32 (max.)	peripheral I/O.)	
8-bit PWM timer	8-bit reload timer operation (toggled output capable) 8-bit resolution PWM operation Operating clock (pulse width count timer output: 0.8 μs, 12.8 μs, 51.2 μs/5 MHz)				
8-bit pulse width count timer	8-bit reload timer operation 8-bit pulse width count operation (continuous measurement capable "H" width, "L" width, or single-cycle measurement capable) Operating clock (0.8 μs, 3.2 μs, 25.6 μs/5 MHz)				
8-bit serial I/O	8 bits One clock selectable from four transfer clocks (one external shift clock, three internal shift clocks: 1.6 μs, 6.4 μs, 25.6 μs/5 MHz) LSB first/MSB first selectability				

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Part number Parameter	MB89821	MB89823	MB89P825	MB89PV820			
UART	5-, 7-, 8-bit transfer capable Internal baud-rate generator (max. 78125 bps/5 MHz)						
LCD controller/ driver	Common output: 4 Segment output: 50 (max.) Operating mode: 1/2 bias, 1/2 duty; 1/3 bias, 1/3 duty; 1/3 bias, 1/4 duty LCD display RAM size: 50 × 4 bits Dividing resistor for LCD driving: Built-in (An external resistor selectable)						
External interrupt	2 channels (edge s	electable) (1 channel a	llso serves as a pulse wi	dth count timer input)			
Standby mode		Sleep mod	de, stop mode				
Process	CMOS						
Operating voltage*2	2.2 V ⁻³ to 6.0 V 2.7 V to 6.0 V						
EPROM for use	MBM27C256A-20 (LCC package)						

^{*1:} The function is selected by the mask option.

■ PACKAGE AND CORRESPONDING PRODUCTS

Package	MB89821 MB89823 MB89P825	MB89PV820
FPT-80P-M11	0	×
MQP-80C-P01	×	0

 \bigcirc : Available \times : Not available

Note: For more information about each package, see section "■ Package Dimensions."

^{*2:} Varies with conditions such as the operating frequency. (See section "■ Electrical Characteristics.")

^{*3:} The operation at less than 2.2 V is assured separately. Please contact FUJITSU LIMITED.

■ DIFFERENCES AMONG PRODUCTS

1. Memory Size

Before evaluating using the piggyback product, verify its differences from the product that will actually be used. Take particular care on the following points:

- On the MB89821, the register bank address upper than 0140_H cannot be used. On the MB89823 and MB89P825, each register bank addresses upper than 0180_H can be used.
- On the MB89P825, addresses BFF0_H to BFF6_H comprise the option setting area, option settings can be read by reading these addresses.
- The stack area, etc., is set at the upper limit of the RAM.

2. Current Consumption

- In the case of the MB89PV820, add the current consumed by the EPROM which is connected to the top socket.
- However, the current consumption in sleep/stop modes is the same. (For more information, see section
 "Electrical Characteristics."

3. Mask Options

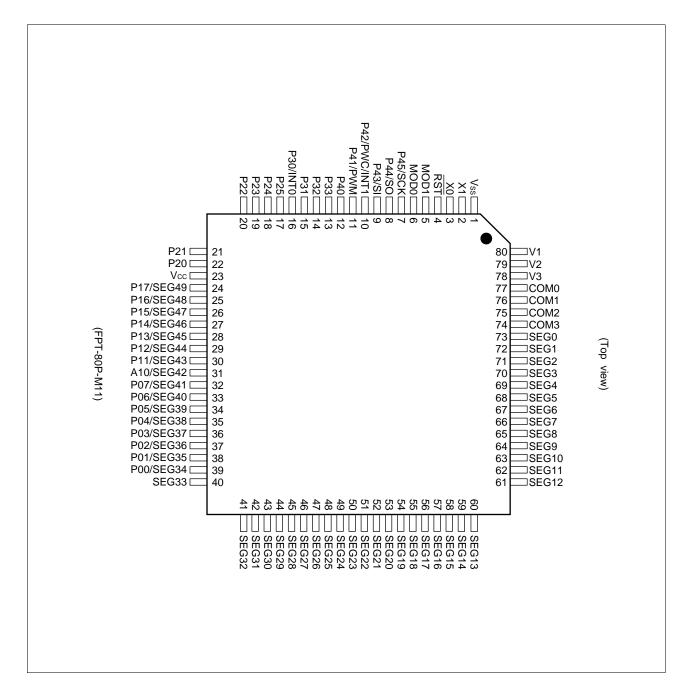
Functions that can be selected as options and how to designate these options vary by the product.

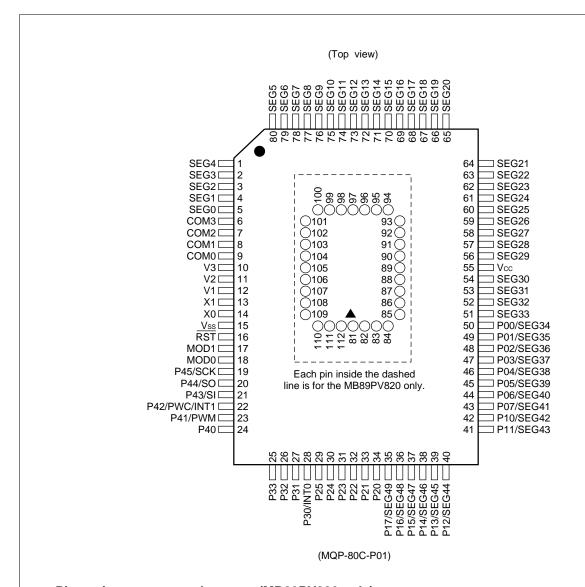
Before using options check section "■ Mask Options."

Take particular care on the following point:

• Options are fixed on the MB89PV820.

I PIN ASSIGNMENT





Pin assignment on package top (MB89PV820 only)

Pin no.	Pin name	Pin no.	Pin name	Pin no.	Pin name	Pin no.	Pin name
81	N.C.	89	A2	97	N.C.	105	ŌĒ
82	V _{PP}	90	A1	98	O4	106	N.C.
83	A12	91	A0	99	O5	107	A11
84	A7	92	N.C.	100	O6	108	A9
85	A6	93	01	101	07	109	A8
86	A5	94	O2	102	O8	110	A13
87	A4	95	О3	103	CE	111	A14
88	A3	96	Vss	104	A10	112	Vcc

N.C.: Internally connected. Do not use.

■ PIN DESCRIPTION

Pin no.		.	Circuit	
QFP*1	MQFP*2	Pin name	type	Function
3	14	X0	Α	Clock crystal oscillator pins
2	13	X1		
6	18	MOD0	В	Operating mode selection pins
5	17	MOD1		Connect directly to Vss.
4	16	RST	С	Reset I/O pin This pin is an N-ch open-drain type with a pull-up resistor, and a hysteresis input type. "L" is output from this pin by an internal reset source (optional function). The internal circuit is initialized by the input of "L".
39 to 32	50 to 43	P00/SEG34 to P07/SEG41	D	General-purpose N-ch open-drain I/O ports Also serve as an LCD controller/driver segment output. The port and segment output are switched by mask option in 8-bit unit.
31 to 24	42 to 35	P10/SEG42 to P17/SEG49	D	General-purpose N-ch open-drain I/O ports Also serve as an LCD controller/driver segment output. The port and segment output are switched by mask option in 4 to 1-bit unit.
22 to 17	34 to 29	P20 to P25	F	General-purpose N-ch open-drain I/O ports A pull-up resistor option is provided.
16	28	P30/INT0	Н	General-purpose input port The input is hysteresis input. Also serves as an external interrupt input (INT0). A pull-up resistor option is provided.
15 to 13	27 to 25	P31 to P33	Н	General-purpose input ports These pins are a hysteresis input type. A pull-up resistor option is provided.
12	24	P40	Е	General-purpose I/O port A pull-up resistor option is provided.
11	23	P41/PWM	E	General-purpose I/O port A pull-up resistor option is provided. Also serves as an 8-bit PWM timer toggle output (PWM).
10	22	P42/PWC/INT1	E	General-purpose I/O port A pull-up resistor option is provided. Also serves as an 8-bit pulse width count timer input (PWC) and an external interrupt input (INT1). The PWC and INT1 input is hysteresis input.
9	21	P43/SI	E	General-purpose I/O port A pull-up resistor option is provided. Also serves as an 8-bit serial I/O and a UART data input (SI). The SI input is hysteresis input.

*1: FPT-80P-M11 (Continued)

*2: MQP-80C-P01

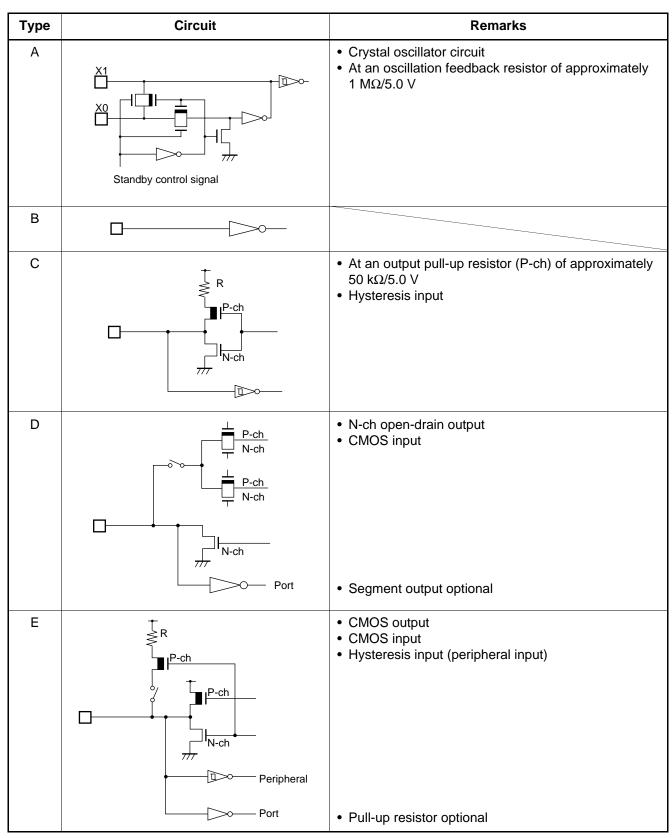
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Pin	no.	Pin name Circuit type		Function
QFP*1	MQFP*2			Function
8	20	P44/SO	E	General-purpose I/O port A pull-up resistor option is provided. Also serves as a serial I/O and a UART data output (SO).
7	19	P45/SCK	Е	General-purpose I/O port A pull-up resistor option is provided. Also serves as a serial I/O and a UART clock I/O (SCK). The SCK input is hysteresis input.
73 to 40	5 to 1, 80 to 56, 54 to 51	SEG0 to SEG33	G	LCD controller/driver segment output pins
77 to 74	9 to 6	COM0 to COM3	G	LCD controller/driver common output pins
80 to 78	12 to 10	V1 to V3	_	LCD driving power supply pins
23	55	Vcc	_	Power supply pin
1	15	Vss	_	Power supply (GND) pin

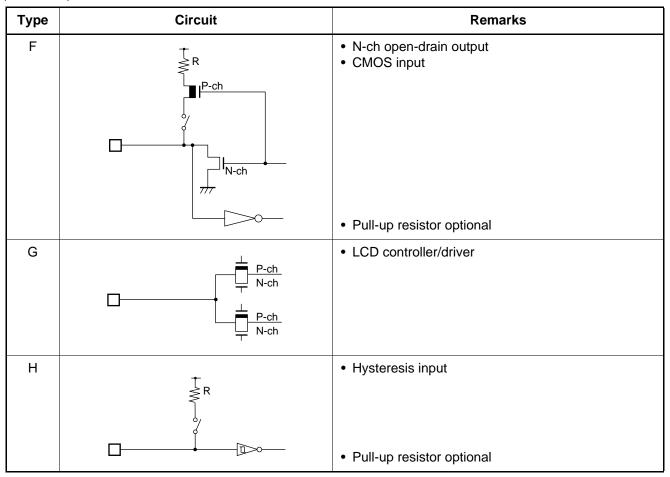
• External EPROM pins (MB89PV820 only)

Pin no.	Pin name	I/O	Function
82	V _{PP}	0	"H" level output pin
83 84 85 86 87 88 89 90	A12 A7 A6 A5 A4 A3 A2 A1 A0	0	Address output pins
93 94 95	O1 O2 O3	I	Data input pins
96	Vss	0	Power supply (GND) pin
98 99 100 101 102	O4 O5 O6 O7 O8	I	Data input pins
103	CE	0	ROM chip enable pin Outputs "H" during standby.
104	A10	0	Address output pin
105	ŌĒ	0	ROM output enable pin Outputs "L" at all times.
107 108 109	A11 A9 A8	0	Address output pins
110	A13	0	
111	A14	0	
112	Vcc	0	EPROM power supply pin
81 92 97 106	N.C.	_	Internally connected pins Be sure to leave them open.

■ I/O CIRCUIT TYPE



(Continued)



■ HANDLING DEVICES

1. Preventing Latchup

Latchup may occur on CMOS ICs if voltage higher than V_{CC} or lower than V_{SS} is applied to input and output pins other than medium- to high-voltage pins or if higher than the voltage which shows on "1. Absolute Maximum Ratings" in section "■ Electrical Characteristics" is applied between V_{CC} and V_{SS}.

When latchup occurs, power supply current increases rapidly and might thermally damage elements. When using, take great care not to exceed the absolute maximum ratings.

Also, take care to prevent the analog power supply (AVcc and AVR) and analog input from exceeding the digital power supply (Vcc) when the analog system power supply is turned on and off.

2. Treatment of Unused Input Pins

Leaving unused input pins open could cause malfunctions. They should be connected to a pull-up or pull-down resistor.

3. Treatment of Power Supply Pins on Microcontrollers with A/D and D/A Converters

Connect to be AVcc = DAVC = Vcc and AVss = AVR = Vss even if the A/D and D/A converters are not in use.

4. Treatment of N.C. Pins

Be sure to leave (internally connected) N.C. pins open.

5. Power Supply Voltage Fluctuations

Although Vcc power supply voltage is assured to operate within the rated range, a rapid fluctuation of the voltage could cause malfunctions, even if it occurs within the rated range. Stabilizing voltage supplied to the IC is therefore important. As stabilization guidelines, it is recommended to control power so that Vcc ripple fluctuations (P-P value) will be less than 10% of the standard Vcc value at the commercial frequency (50 to 60 Hz) and the transient fluctuation rate will be less than 0.1 V/ms at the time of a momentary fluctuation such as when power is switched.

6. Precautions when Using an External Clock

Even when an external clock is used, oscillation stabilization time is required for power-on reset (optional) and wake-up from stop mode.

■ PROGRAMMING TO THE EPROM ON THE MB89P825

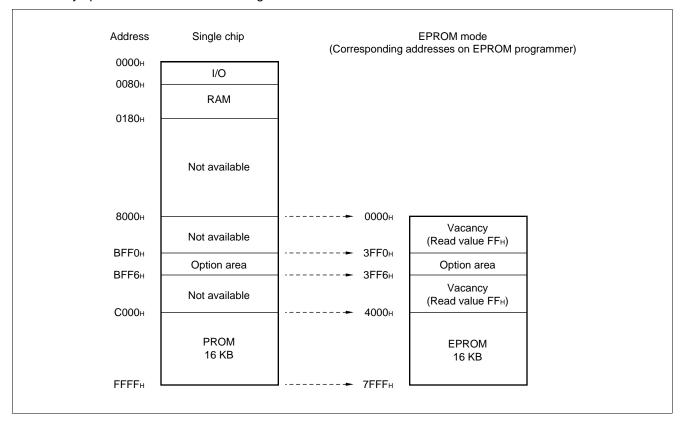
The MB89P825 is an OTPROM (one-time PROM) version for the MB89820 series.

1. Features

- 16-Kbyte PROM on chip
- Options can be set using the EPROM programmer.
- Equivalency to the MBM27C256A in EPROM mode (when programmed with the EPROM programmer)

2. Memory Space

Memory space in EPROM mode is diagrammed below.



3. Programming to the EPROM

In EPROM mode, the MB89P825 functions equivalent to the MBM27C256A. This allows the PROM to be programmed with a general-purpose EPROM programmer (the electronic signature mode cannot be used) by using the dedicated socket adapter.

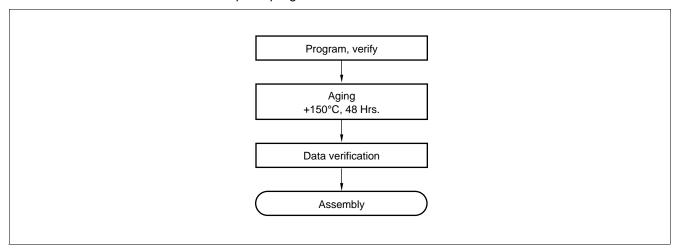
· Programming procedure

- (1) Set the EPROM programmer to the MBM27C256A.
- (2) Load program data into the EPROM programmer at 4000H to 7FFFH (note that addresses C000H to FFFFH while operating as a single chip assign to 4000H to 7FFFH in EPROM mode).

 Load option data into addresses 3FF0H to 3FF5H of the EPROM programmer. (For information about each corresponding option, see "7. OTPROM Option Bit Map."
- (3) Program with the EPROM programmer.

4. Recommended Screening Conditions

High-temperature aging is recommended as the pre-assembly screening procedure for a product for a product with a blanked OTPROM microcomputer program.



5. Programming Yield

All bits cannot be programmed at Fujitsu shipping test to a blanked OTPROM microcomputer, due to its nature. For this reason, a programming yield of 100% cannot be assured at all times.

6. EPROM Programmer Socket Adapter

Package	Compatible socket adapter
FPT-80P-M11	ROM-80QF2-28DP-8L3

Inquiry: Sun Hayato Co., Ltd.: TEL 81-3-3802-5760

7. OTPROM Option Bit Map

	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
3FF0н	Vacancy Readable	Vacancy Readable	Vacancy Readable	Vacancy Readable	Vacancy Readable	Reset pin output 1: Yes 0: No	Oscillation stabilization time 1: 2 ¹⁷ /Fc 0: 2 ¹³ /Fc	Power-on reset 1: Yes 0: No
	Vacancy	Vacancy	Vacancy	Vacancy	Vacancy	Vacancy	Vacancy	Vacancy
3FF1н	Readable	Readable	Readable	Readable	Readable	Readable	Readable	Readable
	Vacancy	Vacancy	Vacancy	Vacancy	Vacancy	Vacancy	Vacancy	Vacancy
3FF2н	Readable	Readable	Readable	Readable	Readable	Readable	Readable	Readable
0550	Vacancy	Vacancy	P25 Pull-up	P24 Pull-up	P23 Pull-up	P22 Pull-up	P21 Pull-up	P20 Pull-up
3FF3н	Readable	Readable	1: No 0: Yes	1: No 0: Yes	1: No 0: Yes	1: No 0: Yes	1: No 0: Yes	1: No 0: Yes
	Vacancy	Vacancy	P45	P44	P43	P42	P41	P40
3FF4 _H	Readable	Readable	Pull-up 1: No 0: Yes	Pull-up 1: No 0: Yes	Pull-up 1: No 0: Yes	Pull-up 1: No 0: Yes	Pull-up 1: No 0: Yes	Pull-up 1: No 0: Yes
	Vacancy	Vacancy	Vacancy	Vacancy	P33	P32	P31	P30
3FF5н	Readable	Readable	Readable	Readable	Pull-up 1: No 0: Yes	Pull-up 1: No 0: Yes	Pull-up 1: No 0: Yes	Pull-up 1: No 0: Yes

Notes: • Set each bit to 1 to erase.

The read value of the vacant bit is 1, unless 0 is written to it.

[•] Do not write 0 to the vacant bit.

■ PROGRAMMING TO THE EPROM WITH PIGGYBACK/EVALUATION DEVICE

1. EPROM for Use

MBM27C256A-20TV

2. Programming Socket Adapter

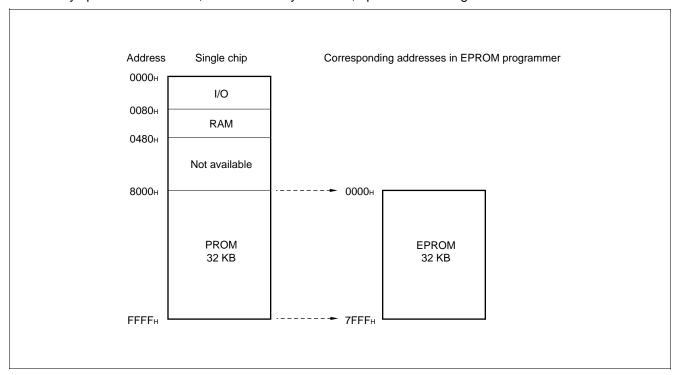
To program to the PROM using an EPROM programmer, use the socket adapter (manufacturer: Sun Hayato Co., Ltd.) listed below.

Package	Adapter socket part number
LCC-32 (Rectangle)	ROM-32LC-28DP-YG

Inquiry: Sun Hayato Co., Ltd.: TEL 81-3-3802-5760

3. Memory Space

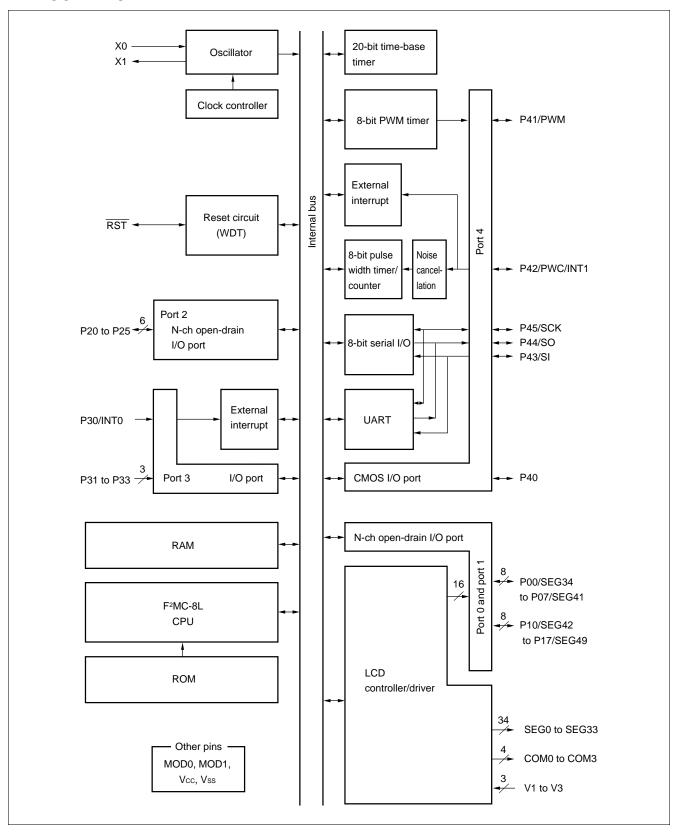
Memory space in each mode, such as 32 Kbyte PROM, option area is diagrammed below.



4. Programming to the EPROM

- (1) Set the EPROM programmer to the MBM27C256A.
- (2) Load program data into the EPROM programmer at 0000_H to 7FFF_H.
- (3) Program to 0000H to 7FFFH with the EPROM programmer.

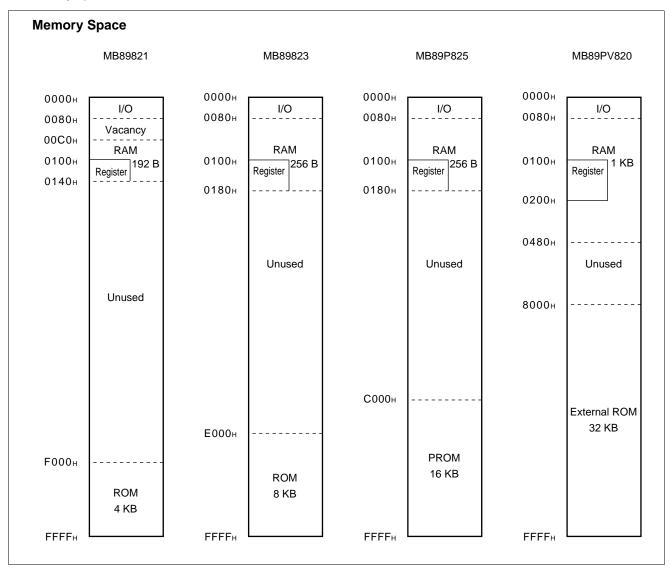
■ BLOCK DIAGRAM



■ CPU CORE

1. Memory Space

The microcontrollers of the MB89820 series offer a memory space of 64 Kbytes for storing all of I/O, data, and program areas. The I/O area is located at the lowest address. The data area is provided immediately above the I/O area. The data area can be divided into register, stack, and direct areas according to the application. The program area is located at exactly the opposite end, that is, near the highest address. Provide the tables of interrupt reset vectors and vector call instructions toward the highest address within the program area. The memory space of the MB89820 series is structured as illustrated below.



2. Registers

The F²MC-8L family has two types of registers; dedicated registers in the CPU and general-purpose registers in the memory. The following dedicated registers are provided:

Program counter (PC): A 16-bit register for indicating instruction storage positions

Accumulator (A): A 16-bit temporary register for storing arithmetic operations, etc. When the

instruction is an 8-bit data processing instruction, the lower byte is used.

Temporary accumulator (T): A 16-bit register which performs arithmetic operations with the accumulator

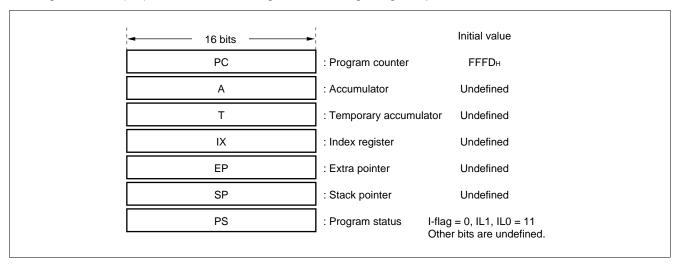
When the instruction is an 8-bit data processing instruction, the lower byte is used.

Index register (IX): A 16-bit register for index modification

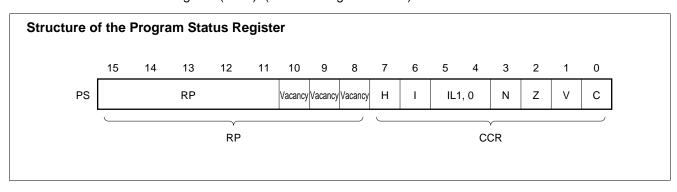
Extra pointer (EP): A 16-bit pointer for indicating a memory address

Stack pointer (SP): A 16-bit register for indicating a stack area

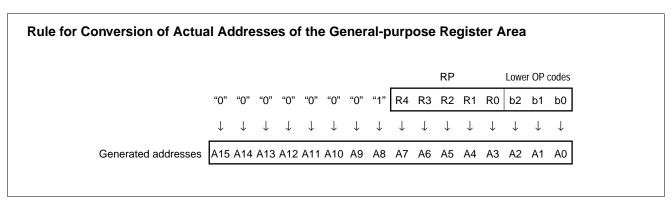
Program status (PS): A 16-bit register for storing a register pointer, a condition code



The PS can further be divided into higher 8 bits for use as a register bank pointer (RP) and the lower 8 bits for use as a condition code register (CCR). (See the diagram below.)



The RP indicates the address of the register bank currently in use. The relationship between the pointer contents and the actual address is based on the conversion rule illustrated below.



The CCR consists of bits indicating the results of arithmetic operations and the contents of transfer data and bits for control of CPU operations at the time of an interrupt.

H-flag: Set when a carry or a borrow from bit 3 to bit 4 occurs as a result of an arithmetic operation. Cleared otherwise. This flag is for decimal adjustment instructions.

I-flag: Interrupt is allowed when this flag is set to 1. Interrupt is prohibited when the flag is set to 0. Set to 0 when reset.

IL1, 0: Indicates the level of the interrupt currently allowed. Processes an interrupt only if its request level is higher than the value indicated by this bit.

IL1	IL0	Interrupt level	High-low
0	0	1	High
0	1	·	†
1	0	2	
1	1	3	Low = no interrupt

N-flag: Set if the MSB is set to 1 as the result of an arithmetic operation. Cleared when the bit is set to 0.

Z-flag: Set when an arithmetic operation results in 0. Cleared otherwise.

V-flag: Set if the complement on 2 overflows as a result of an arithmetic operation. Reset if the overflow does not occur.

C-flag: Set when a carry or a borrow from bit 7 occurs as a result of an arithmetic operation. Cleared otherwise. Set to the shift-out value in the case of a shift instruction.

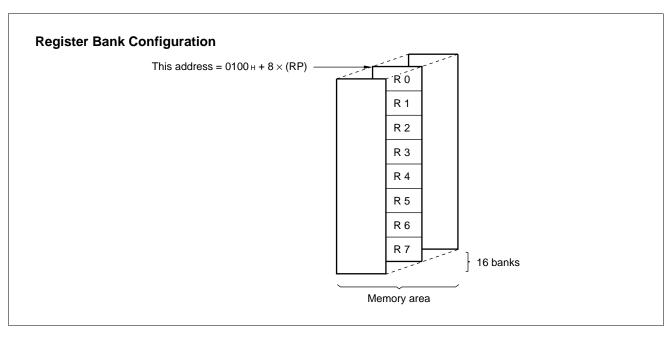
The following general-purpose registers are provided:

General-purpose registers: An 8-bit register for storing data

The general-purpose registers are 8 bits and located in the register banks of the memory. One bank contains eight registers and up to a total of 16 banks can be used on the MB89823 (RAM 256×8 bits). The bank currently in use is indicated by the register bank pointer (RP).

Note: The number of register banks that can be used varies with the RAM size.

MB89821	0100н to 013Fн	8 banks
MB89823	0100н to 017Fн	16 banks
MB89P825	0100н to 017Fн	16 banks
MB89PV820	0100н to 01FFн	32 banks



■ I/O MAP

Address	Read/write	Register name	Register description
00н	(R/W)	PDR0	Port 0 data register
01н		1	Vacancy
02н	(R/W)	PDR1	Port 1 data register
03н			Vacancy
04н	(R/W)	PDR2	Port 2 data register
05н			Vacancy
06н			Vacancy
07н			Vacancy
08н	(R/W)	STBC	Standby control register
09н	(R/W)	WDTC	Watchdog timer control register
0Ан	(R/W)	TBCR	Time-base timer control register
0Вн		1	Vacancy
0Сн	(R)	PDR3	Port 3 data register
0Dн			Vacancy
0Ен	(R/W)	PDR4	Port 4 data register
0Fн	(W)	DDR4	Port 4 data direction register
10н			Vacancy
11н			Vacancy
12н	(R/W)	CNTR	PWM timer control register
13н	(W)	COMR	PWM timer compare register
14н	(R/W)	PCR1	PWC pulse width control register 1
15н	(R/W)	PCR2	PWC pulse width control register 2
16н	(R/W)	RLBR	PWC reload buffer register
17н	(R/W)	NCCR	PWC noise cancellation control register
18н			Vacancy
19н			Vacancy
1Ан			Vacancy
1Вн			Vacancy
1Сн	(R/W)	SMR	Serial mode register
1Dн	(R/W)	SDR	Serial data register
1Ен			Vacancy
1 Fн			Vacancy

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Address	Read/write	Register name	Register description				
20н	(R/W)	SMC1	UART serial mode control register 1				
21н	(R/W)	SRC	UART serial rate control register				
22н	(R/W)	SSD	UART serial status/data register				
23н	(R/W)	SIDR/SODR	UART serial data register				
24н	(R/W)	SMC2	UART serial mode control register 2				
25н			Vacancy				
26н			Vacancy				
27н			Vacancy				
28н			Vacancy				
29н			Vacancy				
2Ан			Vacancy				
2Вн		Vacancy					
2Сн		Vacancy					
2Dн		Vacancy					
2Ен			Vacancy				
2Fн			Vacancy				
30н	(R/W)	EIC1	External interrupt 1 control register				
31н to 5Fн			Vacancy				
60н to 78н	(R/W)	VRAM	Display data RAM				
79н	(R/W)	LCR1	LCD controller/driver control register				
7Ан	(R/W)	SEGR	Segment output selection register				
7Вн		1	Vacancy				
7Сн	(W)	ILR1	Interrupt level setting register 1				
7Dн	(W)	ILR2	Interrupt level setting register 2				
7Ен	(W)	ILR3	Interrupt level setting register 3				
7 Fн		1	Vacancy				

Note: Do not use vacancies.

■ ELECTRICAL CHARACTERISTICS

1. Absolute Maximum Ratings

(Vss = 0.0 V)

Devementer	Comple ed	Va	lue	Unit	Remarks
Parameter	Symbol	Min.	Max.	Unit	Remarks
Power supply voltage	Vcc	Vss - 0.3	Vss + 7.0	V	
LCD power supply voltage	V3	Vss - 0.3	Vss + 7.0	V	V3 pin
	VII	Vss - 0.3	Vcc + 0.3	V	V _{II} must not exceed V _{SS} + 7.0 V. Except P00 to P07 and P10 to P17 for the MB89P825/PV820, and P20 to P25 without a pull-up resistor
Input voltage	Vı2	Vss - 0.3	Vss + 7.0	V	P00 to P07 and P10 to P17 (when selected as ports) for the MB89821/823, and P20 to P25 without a pull-up resistor
	Vıз	Vss - 0.3	V3 + 0.3	V	P00 to P07 and P10 to P17 for the MB89P825/PV820
	V ₀₁	Vss - 0.3	Vcc + 0.3	V	Vo ₁ must not exceed Vss + 7.0 V. Except P00 to P07 and P10 to P17 for the MB89P825/PV820, and P20 to P25 without a pull-up resistor
Output voltage	V _{O2}	Vss - 0.3	Vss + 7.0	V	P00 to P07 and P10 to P17 (when selected as ports) for the MB89821/823, and P20 to P25 without a pull-up resistor
	V _{O3}	Vss - 0.3	V3 + 0.3	V	P00 to P07 and P10 to P17 for the MB89P825/PV820
"L" level output current	lol	_	10	mA	Except power supply pins
"L" level average output current	lolav	_	4	mA	Average value (operating current × operating rate) Except power supply pins
Total "L" level output current	Σ loL	_	40	mA	
"H" level output current	Іон	_	- 5	mA	Except power supply pins
"H" level average output current	Іонаv	_	-2	mA	Average value (operating current × operating rate) Except power supply pins
Total "H" level output current	ΣІон	_	-10	mA	
Power consumption	PD	_	300	mW	
Operating temperature	TA	-40	+85	°C	
Storage temperature	Tstg	- 55	+150	°C	

Precautions: Permanent device damage may occur if the above "Absolute Maximum Ratings" are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

2. Recommended Operating Conditions

(Vss = 0.0 V)

Parameter	Symbol	Value		Unit	Remarks	
raidilletei	Symbol	Min.	Max.	Oilit	Kemarks	
		2.2*	6.0*	V	Normal operation assurance range*	
Power supply voltage	Vcc	1.5	6.0	V	Retains the RAM state in stop mode	
LCD power supply voltage	V3	Vss	6.0	V	V3 pin LCD power supply range. The optimum value is dependent on the element in use.	
Operating temperature	TA	-40	+85	°C		

^{*:} The minimum operating power supply voltage varies with the operating frequency.

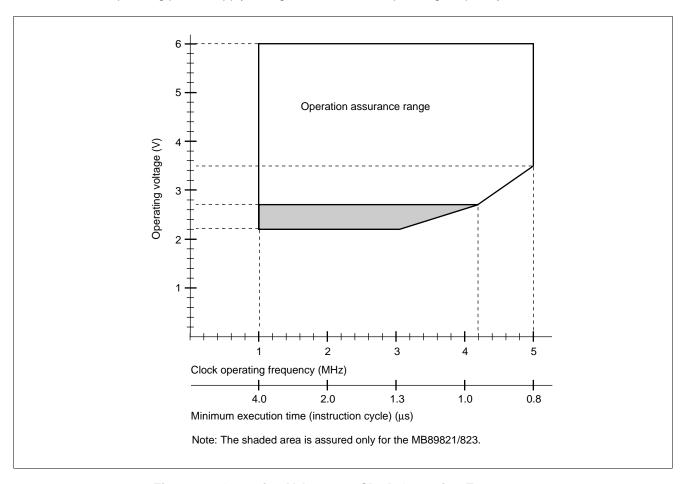


Figure 1 Operating Voltage vs. Clock Operating Frequency

Figure 1 indicates the operating frequency of the external oscillator at an instruction cycle of 4/Fc.

3. DC Characteristics

 $(Vcc = V3 = +5.0 \text{ V}, Vss = 0.0 \text{ V}, T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C})$

				(VCC = V3)	Value		U V, IA	$x = -40^{\circ}C \text{ to } +85^{\circ}C)$
Parameter	Symbol	Pin	Condition	Min.	Typ.	Max.	Unit	Remarks
"H" level input	Vін	P00 to P07, P10 to P17, P20 to P25, P30 to P33, P40 to P45	_	0.7 Vcc*1	—	Vcc + 0.3*1	V	
	Vihs	RST, MOD0, MOD1, INT0, SCK, SI, PWC/INT1	_	0.8 Vcc	_	Vcc + 0.3	V	
V _L "L" level input		P00 to P07, P10 to P17, P22 to P25, P30 to P33, P40 to P45	_	Vcc - 0.3	_	0.3 Vcc*1	V	
voltage	VILS	RST, MOD0, MOD1, INT0, SCK, SI, PWC/INT1	_	Vss - 0.3	_	0.2 Vcc	V	
Open-drain output pin application voltage	V _D	P20 to P25, P00 to P07, P10 to P17	_	Vss - 0.3	_	Vcc + 6.0	V	P00 to P07 and P10 to P17 (when selected as ports) for the MB89821/823, and P20 to P25 without pull-up resistor
"H" level output voltage	Vон	P40 to P45	Iон = −2 mA	2.4	_	_	V	
"L" level output voltage	V _{OL1}	P00 to P07, P10 to P17, P20 to P25, P40 to P45	IoL = 1.8 mA	_	_	0.4	V	
	V _{OL2}	RST	IoL = 4 mA		_	0.4	V	
		MOD0, MOD1, P30 to P33, P40 to P45		_	_	±5	μА	Without pull-up resistor for the MB89821/823
Input leakage current (Hi-z output leakage current)	Іш	MOD0, MOD1, P00 to P07, P10 to P17, P30 to P33, P40 to P45	0.0 V < Vı < Vcc	_	_	±5	μА	Without pull-up resistor for the MB89P825/PV820
	I _{LI2}	P00 to P07, P10 to P17, P20 to P25	0.0 V < Vı < 6.0 V	_	_	±1	μΑ	Without pull-up resistor for the MB89821/823
	ILIZ	P20 to P25	0.0 V \ VI\ 0.0 V	_	_	±1	μА	Without pull-up resistor for the MB89P825/PV820

(Continued)

(Continued)

 $(Vcc = V3 = +5.0 \text{ V}, Vss = 0.0 \text{ V}, T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C})$

Dorometer	Cumbal	l Pin	Condition		Value		Unit	Remarks
Parameter	Symbol	Pin	Condition	Min.	Тур.	Max.	Unit	Remarks
Pull-up resistance	Rpull	P20 to P25, P30 to P33, P40 to P45, RST	V1 = 0.0 V	25	50	100	kΩ	With pull-up resistor
Common output impedance	Rvcом	COM0 to COM3	V1 to V3 = +5.0 V	_	_	2.5	kΩ	
Segment output impedance	Rvseg	SEG0 to SEG49	V1 to V3 = +5.0 V	_	_	15	kΩ	
LCD divided resistance	RLCD	_	Between V3 and Vss	30	60	120	kΩ	
LCD leakage current	ILCDL	V1 to V3, COM0 to COM3, SEG0 to SEG49	_	_	_	±1	μА	
	Icc	100	Fc = 5 MHz t _{inst*3} = 0.8 μs	_	3.5	5.0	mA	MB89821, MB89823, MB89PV820
			·	_	4.0	6.5	mA	MB89P825
Power supply current-2	lccs Vcc	Vcc	Fc = 5 MHz t _{inst} *3 = 0.8 μs Sleep mode	_	1.1	1.7	mA	MB89821, MB89823, MB89PV820, MB89P825
	Іссн		T _A = +25°C Stop mode	_	0.1	1	μА	MB89821, MB89823
	ICCH			_	0.1	10	μΑ	MB89PV820, MB89P825
Input capacitance	CIN	Other than Vcc and Vss	f = 1 MHz	_	10	_	pF	

^{*1:} The input voltage to P00 to P07 and P10 to P17 for the MB89P825/PV820 must not exceed the LCD power supply voltage (V3 pin voltage).

In the case of the MB89PV820, the current consumed by the connected EPROM and ICE is not included.

^{*2:} The measurement condition of power supply current is as follows: the external clock, open output pins and the external LCD dividing resistor.

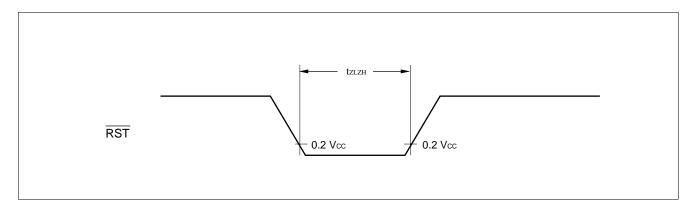
^{*3:} For information on t_{inst}, see "(4) Instruction Cycle" in "4. AC Characteristics."

4. AC Characteristics

(1) Reset Timing

 $(Vcc = +5.0 V\pm 10\%, Vss = 0.0 V, TA = -40^{\circ}C to +85^{\circ}C)$

Parameter	Symbol	Condition	Va	lue	Unit	Remarks	
Parameter	Syllibol	Condition	Min.	Max.	Ullit	Remarks	
RST "L" pulse width	t zlzh	_	48 txcyl	_	ns		



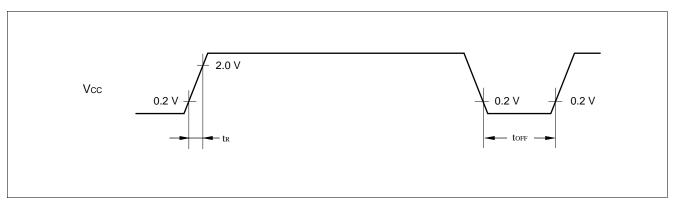
(2) Power-on Reset

 $(Vss = 0.0 V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C)$

Parameter	Symbol	Condition	Va	lue	Unit	Remarks	
raiailletei	Syllibol	Condition	Min.	Max.	Ullit	ixemarks	
Power supply rising time	t _R		_	50	ms	Power-on reset function only	
Power supply cut-off time	toff	_	1	_	ms	Due to repeated operations	

Note: Make sure that power supply rises within the selected oscillation stabilization time.

If power supply voltage needs to be varied in the course of operation, a smooth voltage rise is recommended.

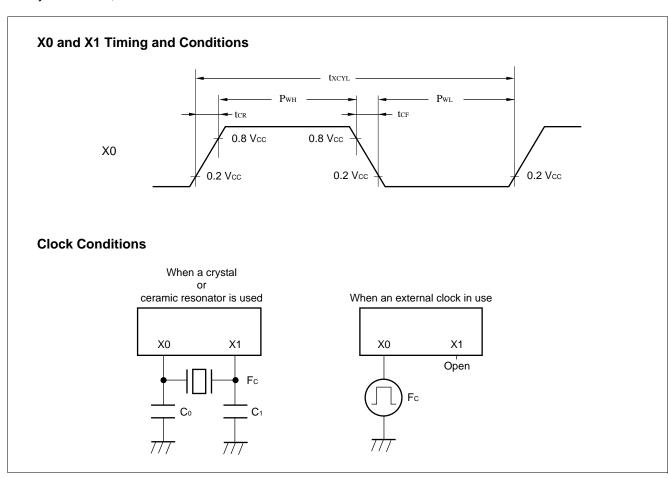


(3) Clock Timing

 $(Vss = 0.0 V, T_A = -40^{\circ}C \text{ to } +85^{\circ}C)$

Parameter	Sym-	Pin	Condition	Value			Unit	Remarks	
Parameter	bol	FIII	Condition	Min.	Тур.	Max.	Offic	iveillai ks	
Clock frequency	Fc			1	_	5	MHz		
Clock cycle time	txcyL	X0, X1		200	_	1000	ns	Crystal or ceramic resonator	
Input clock duty ratio*	duty			30	_	70	%	External clock	
Input clock rising/ falling time	tcr tcr	X0		_	_	10	ns	External clock	

^{*:} duty = Pwh/thcyl, Pwl/thcyl



(4) Instruction Cycle

Parameter	Symbol	Value (typical)	Unit	Remarks
Instruction cycle (minimum execution time)	tinst	4/Fc	μs	$t_{inst} = 0.8 \mu s$ when operating at $F_C = 5 MHz$

(5) Serial I/O Timing

 $(Vcc = +5.0 V\pm 10\%, Vss = 0.0 V, TA = -40^{\circ}C to +85^{\circ}C)$

Parameter	Symbol	Pin	Condition	Va	lue	Unit	Remarks
Farameter	Syllibol	FIII	Condition	Min.	Max.	Ullit	Remarks
Serial clock cycle time	tscyc	SCK		2 tinst*	_	μs	
$SCK \downarrow \rightarrow SO$ time	tslov	SCK, SO	Internal shift clock mode	-200	200	ns	
Valid SI → SCK ↑	tıvsh	SI, SCK		0.5 tinst*	_	μs	
$SCK \uparrow \to valid \; SI \; hold \; time$	t shix	SCK, SI		0.5 tinst*	_	μs	
Serial clock "H" pulse width	tshsl	SCK		1 tinst*	_	μs	
Serial clock "L" pulse width	t slsh	SUK	External	1 tinst*	_	μs	
$SCK \downarrow \to SO$ time	tslov	SCK, SO	shift clock	0	200	ns	
Valid SI → SCK ↑	tıvsh	SI, SCK	mode	0.5 tinst*	_	μs	
$SCK \uparrow \rightarrow valid SI hold time$	tsнıx	SCK, SI		0.5 tinst*		μs	

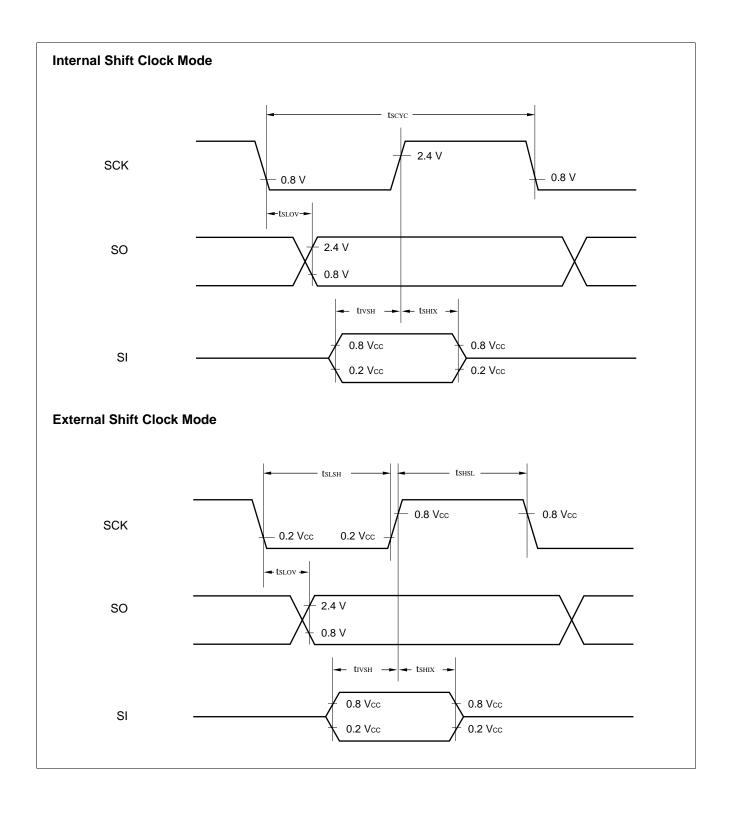
^{*:} For information on tinst, see "(4) Instruction Cycle."

(6) UART Timing

 $(Vcc = +5.0 V\pm 10\%, Vss = 0.0 V, T_A = -40^{\circ}C to +85^{\circ}C)$

Parameter	Symbol	Pin	Condition	Value		Unit	Remarks
raiailletei	Syllibol	FIII	Condition	Min.	Max.	Oilit	Remarks
Serial clock cycle time	tscyc	SCK		2 tinst*	_	μs	
$SCK \downarrow \to SO$ time	tslov	SCK, SO	Internal shift clock mode	-200	200	ns	
Valid SI → SCK ↑	tıvsh	SI, SCK		0.5 tinst*		μs	
$SCK \uparrow \rightarrow valid SI hold time$	t shix	SCK, SI		0.5 tinst*		μs	
Serial clock "H" pulse width	t shsl	SCK		1 tinst*		μs	
Serial clock "L" pulse width	t slsh	SUR	External	1 tinst*		μs	
$SCK \downarrow \to SO$ time	tslov	SCK, SO SI, SCK	shift clock	0	200	ns	
Valid SI → SCK ↑	tıvsh		mode	0.5 tinst*	_	μs	
$SCK \uparrow \rightarrow valid SI hold time$	t shix	SCK, SI		0.5 tinst*	_	μs	

^{*:} For information on tinst, see "(4) Instruction Cycle."

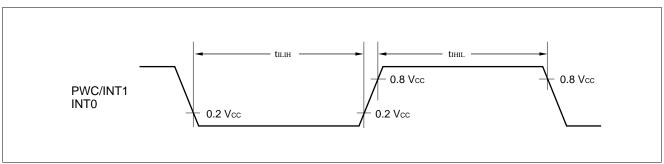


(7) Peripheral Input Timing

 $(Vcc = +5.0 V\pm 10\%, Vss = 0.0 V, T_A = -40^{\circ}C to +85^{\circ}C)$

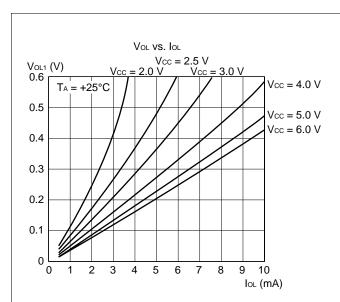
Parameter	Symbol	Pin	Condition	Va	lue	Unit	Remarks
Parameter Symbol		FIII	Condition	Min.	Max.	Offic	Remarks
Peripheral input "H" pulse width	tішн	PWC/INT1		2 tinst*	_	μs	
Peripheral input "L" pulse width	tiHIL	INT0	_	2 tinst*	_	μs	

*: For information on t_{inst}, see "(4) Instruction Cycle."

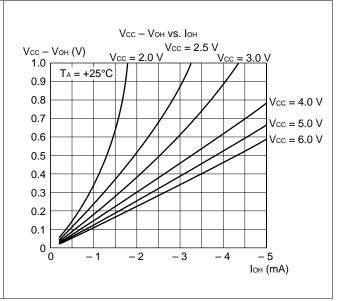


■ EXAMPLE CHARACTERISTICS

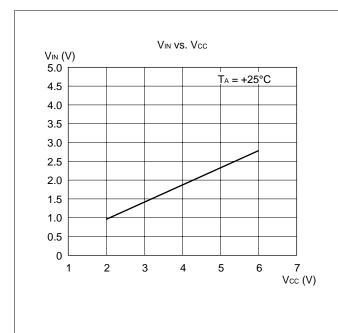
(1) "L" Level Output Voltage



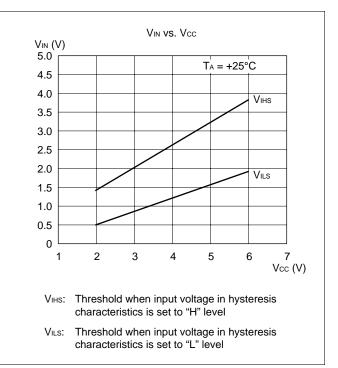
(2) "H" Level Output Voltage



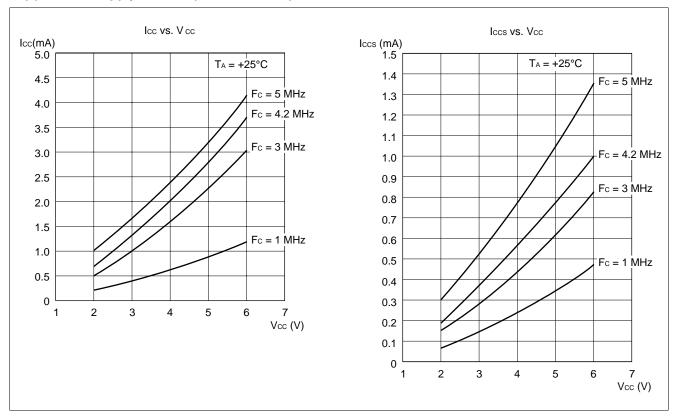
(3) "H" Level Input Voltage/"L" Level Input Voltage (CMOS Input)



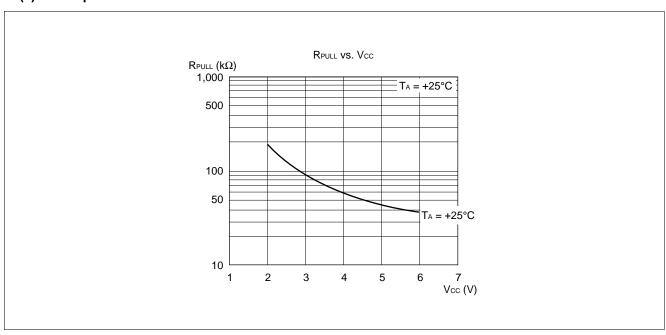
(4) "H" level Input Voltage/"L" Level Input Voltage (CMOS Hysteresis Input)



(5) Power Supply Current (External Clock)



(6) Pull-up Resistance



■ INSTRUCTIONS

Execution instructions can be divided into the following four groups:

- Transfer
- Arithmetic operation
- Branch
- Others

Table 1 lists symbols used for notation of instructions.

Table 1 Instruction Symbols

Symbol	Meaning
dir	Direct address (8 bits)
off	Offset (8 bits)
ext	Extended address (16 bits)
#vct	Vector table number (3 bits)
#d8	Immediate data (8 bits)
#d16	Immediate data (16 bits)
dir: b	Bit direct address (8:3 bits)
rel	Branch relative address (8 bits)
@	Register indirect (Example: @A, @IX, @EP)
А	Accumulator A (Whether its length is 8 or 16 bits is determined by the instruction in use.)
AH	Upper 8 bits of accumulator A (8 bits)
AL	Lower 8 bits of accumulator A (8 bits)
Т	Temporary accumulator T (Whether its length is 8 or 16 bits is determined by the instruction in use.)
TH	Upper 8 bits of temporary accumulator T (8 bits)
TL	Lower 8 bits of temporary accumulator T (8 bits)
IX	Index register IX (16 bits)

(Continued)

(Continued)

Symbol	Meaning
EP	Extra pointer EP (16 bits)
PC	Program counter PC (16 bits)
SP	Stack pointer SP (16 bits)
PS	Program status PS (16 bits)
dr	Accumulator A or index register IX (16 bits)
CCR	Condition code register CCR (8 bits)
RP	Register bank pointer RP (5 bits)
Ri	General-purpose register Ri (8 bits, i = 0 to 7)
×	Indicates that the very \times is the immediate data. (Whether its length is 8 or 16 bits is determined by the instruction in use.)
(×)	Indicates that the contents of \times is the target of accessing. (Whether its length is 8 or 16 bits is determined by the instruction in use.)
((×))	The address indicated by the contents of \times is the target of accessing. (Whether its length is 8 or 16 bits is determined by the instruction in use.)

Columns indicate the following:

Mnemonic: Assembler notation of an instruction

~: Number of instructions

#: Number of bytes

Operation: Operation of an instruction

TL, TH, AH: A content change when each of the TL, TH, and AH instructions is executed. Symbols in

the column indicate the following:

• "-" indicates no change.

• dH is the 8 upper bits of operation description data.

• AL and AH must become the contents of AL and AH immediately before the instruction

is executed.

• 00 becomes 00.

N, Z, V, C: An instruction of which the corresponding flag will change. If + is written in this column,

the relevant instruction will change its corresponding flag.

OP code: Code of an instruction. If an instruction is more than one code, it is written according to

the following rule:

Example: 48 to 4F ← This indicates 48, 49, ... 4F.

 Table 2
 Transfer Instructions (48 instructions)

Mnemonic	~	#	Operation	TL	TH	AH	NZVC	OP code
MOV dir,A	3	2	(dir) ← (A)	-	_	_		45
MOV @IX +off,A	4	2	$((IX) + off) \leftarrow (A)$	_	_	_		46
MOV ext,A	4	3	$(ext) \leftarrow (A)$	_	_	_		61
MOV @EP,A	3	1	((EP)) ← (A)	_	_	_		47
MOV Ri,A	3	1	(Ri) ← (A)	_	_	_		48 to 4F
MOV A,#d8	2	2	$(A) \leftarrow d8$	AL	_	_	++	04
MOV A,dir	3	2	$(A) \leftarrow (dir)$	AL	_	_	++	05
MOV A,@IX +off	4	2	$(A) \leftarrow ((IX) + off)$	AL	_	_	++	06
MOV A,ext	4	3	$(A) \leftarrow (ext)$	AL	_	_	++	60
MOV A,@A	3	1	$(A) \leftarrow (A)$	AL	_	_	++	92
MOV A,@EP	3	1	(A) ← ((EP))	AL	_	_	++	07
MOV A,Ri	3	1	$(A) \leftarrow (Ri)$	AL	_	_	++	08 to 0F
MOV dir,#d8	4	3	$(dir) \leftarrow d8$	_	_	_		85
MOV @IX +off,#d8	5	3	$((IX) + off) \leftarrow d8$	_	_	_		86
MOV @FR.#d8	4	2	((EP)) ← d8	_	_	_		87
MOV @ L1,#d0	4	2	((Ei)) ← d8	_	_	_		88 to 8F
MOVW dir,A	4	2	$(dir) \leftarrow dd$ $(dir) \leftarrow (AH), (dir + 1) \leftarrow (AL)$	_	_	_		D5
MOVW @IX +off,A	5	2	$((IX) \leftarrow (AH), (AH),$	_	_	_		D5 D6
INOVVV @IX +OII,A	5		$((IX) + 0II) \leftarrow (AII),$ $((IX) + 0II) \leftarrow (AL)$	_	_	_		D6
MOVW ext,A	_	2						D4
,	5	3	$(ext) \leftarrow (AH), (ext + 1) \leftarrow (AL)$	-	_	_		D4 D7
MOVW @EP,A	4 2	1	$((EP)) \leftarrow (AH), ((EP) + 1) \leftarrow (AL)$	_	_	_		
MOVW EP,A		1	(EP) ← (A)	_	_	_		E3
MOVW A,#d16	3	3	$(A) \leftarrow d16$	AL	AH	dH	++	E4
MOVW A,dir	4	2	$(AH) \leftarrow (dir), (AL) \leftarrow (dir + 1)$	AL	AH	dH	++	C5
MOVW A,@IX +off	5	2	$(AH) \leftarrow ((IX) + off),$	AL	AH	dH	++	C6
1400 044 4	_	•	$(AL) \leftarrow ((IX) + off + 1)$					0.4
MOVW A,ext	5	3	$(AH) \leftarrow (ext), (AL) \leftarrow (ext + 1)$	AL	AH	dH	++	C4
MOVW A,@A	4	1	$(AH) \leftarrow ((A)), (AL) \leftarrow ((A)) + 1)$	AL	AH	dH	++	93
MOVW A,@EP	4	1	$(AH) \leftarrow ((EP)), (AL) \leftarrow ((EP) + 1)$	AL	AH	dH	++	C7
MOVW A,EP	2	1	(A) ← (EP)	_	_	dH		F3
MOVW EP,#d16	3	3	(EP) ← d16	_	_	_		E7
MOVW IX,A	2	1	$(IX) \leftarrow (A)$	_	_			E2
MOVW A,IX	2	1	$(A) \leftarrow (IX)$	_	_	dH		F2
MOVW SP,A	2	1	$(SP) \leftarrow (A)$	_	_	_		E1
MOVW A,SP	2	1	(A) ← (SP)	_	_	dH		F1
MOV @A,T	3	1	$((A)) \leftarrow (T)$	_	_	_		82
MOVW @A,T	4	1	$(\text{ (A) }) \leftarrow (\text{TH}), (\text{ (A) + 1}) \leftarrow (\text{TL})$	_	_	_		83
MOVW IX,#d16	3	3	(IX) ← d16	_	_	_		E6
MOVW A,PS	2	1	(A) ← (PS)	_	_	dΗ		70
MOVW PS,A	2	1	$(PS) \leftarrow (A)$	_	_	_	++++	71
MOVW SP,#d16	3	3	(SP) ← d16	_	_	_		E5
SWAP	2	1	$(AH) \leftrightarrow (AL)$	_	_	AL		10
SETB dir: b	4	2	(dir): b ← 1	_	_	_		A8 to AF
CLRB dir: b	4	2	(dir): b ← 0	_	_	_		A0 to A7
XCH A,T	2	1	$(AL) \leftrightarrow (TL)$	AL	_	_		42
XCHW A,T	3	1	$(A) \leftrightarrow (T)$	AL	AH	dH		43
XCHW A,EP	3	1	$(A) \leftrightarrow (EP)$	_	_	dH		F7
XCHW A,IX	3	1	$(A) \leftrightarrow (IX)$	_	_	dH		F6
XCHW A,SP	3	1	$(A) \leftrightarrow (SP)$	_	_	dH		F5
MOVW A,PC	2	1	$(A) \leftarrow (PC)$	_	_	dH		FO
	_	·	() ()			~		. 5

Notes: • During byte transfer to A, $T \leftarrow A$ is restricted to low bytes.

• Operands in more than one operand instruction must be stored in the order in which their mnemonics are written. (Reverse arrangement of F²MC-8 family)

 Table 3
 Arithmetic Operation Instructions (62 instructions)

Mnemonic	~	#	Operation	TL	TH	AH	NZVC	OP code
ADDC A,Ri	3	1	$(A) \leftarrow (A) + (Ri) + C$	_	_	_	++++	28 to 2F
ADDC A,#d8	2	2	$(A) \leftarrow (A) + d8 + C$	_	_	_	++++	24
ADDC A,dir	3	2	$(A) \leftarrow (A) + (dir) + C$	_	_	_	++++	25
ADDC A,@IX +off	4	2	$(A) \leftarrow (A) + ((IX) + off) + C$	_	_	_	++++	26
ADDC A,@EP	3	1	$(A) \leftarrow (A) + ((EP)) + C$	_	_		++++	27
ADDCW A	3	1	$(A) \leftarrow (A) + (T) + C$	_	_	dH	++++	23
ADDC A	2	1	$(AL) \leftarrow (AL) + (TL) + C$	_	_	_	++++	22
SUBC A,Ri	3	1	$(A) \leftarrow (A) - (Ri) - C$	_	_	_	++++	38 to 3F
SUBC A,#d8	2	2	$(A) \leftarrow (A) - d8 - C$	_	_	_	++++	34
SUBC A @IV . off	3 4	2 2	$(A) \leftarrow (A) - (dir) - C$	_	_	_	++++	35
SUBC A @ ED			$(A) \leftarrow (A) - ((IX) + off) - C$	_	_	_	++++	36
SUBC A,@EP	3	1	$(A) \leftarrow (A) - ((EP)) - C$	_	_	- -	++++	37
SUBCW A	2	1	$(A) \leftarrow (T) - (A) - C$	_	_	dH	++++	33
SUBC A	4	1	$(AL) \leftarrow (TL) - (AL) - C$	_	_	_	++++	32 C0 to CF
INC Ri INCW EP	3	1	$(Ri) \leftarrow (Ri) + 1$	_	_	_	+++-	C8 to CF
INCW EP	3	1	$(EP) \leftarrow (EP) + 1$	_	_	_		C3 C2
INCW IX	3		$(IX) \leftarrow (IX) + 1$	_	_	4U		C2 C0
DEC Ri	4	1	$(A) \leftarrow (A) + 1$	_	_	dH –	++	D8 toDF
DEC KI	3	1	$(Ri) \leftarrow (Ri) - 1$		_	_	+++-	D8 10DF
DECW EF	3	1	$(EP) \leftarrow (EP) - 1$	_	_	_		D3 D2
DECW A	3	1	$(IX) \leftarrow (IX) - 1$ $(A) \leftarrow (A) - 1$	_	_	dH	++	D2 D0
MULU A	19	1	$(A) \leftarrow (A) - 1$ $(A) \leftarrow (AL) \times (TL)$		_	dH		01
DIVU A	21	1	$(A) \leftarrow (AL) \wedge (1L)$ $(A) \leftarrow (T) / (AL), MOD \rightarrow (T)$	dL	00	00		11
ANDW A	3	1	$(A) \leftarrow (1) \land (AL), \text{NIOD} \rightarrow (1)$ $(A) \leftarrow (A) \land (T)$		_	dH	+ + R -	63
ORW A	3	1	$(A) \leftarrow (A) \land (1)$ $(A) \leftarrow (A) \lor (T)$	_	_	dH	++R-	73
XORW A	3	1	$(A) \leftarrow (A) \vee (T)$ $(A) \leftarrow (A) \vee (T)$	_	_	dH	++R-	53
CMP A	2	1	(TL) – (AL)	_	_	_	++++	12
CMPW A	3	1	(T) - (A)	_	_	_	++++	13
RORC A	2	1	, , , ,	_	_	_	++-+	03
			\rightarrow C \rightarrow A \square					
ROLC A	2	1	$C \leftarrow A \leftarrow$	_	_	_	++-+	02
CMP A,#d8	2	2	(A) – d8	_	_	_	++++	14
CMP A,dir	3	2	(A) – (dir)	_	_	_	++++	15
CMP A,@EP	3	1	(A) – ((EP))	_	_	_	++++	17
CMP A,@IX +off	4	2	(A) - ((IX) + off)	_	_	_	++++	16
CMP A,Ri	3	1	(A) – (Ri)	_	_	_	++++	18 to 1F
DAA	2	1	Decimal adjust for addition	_	_	_	++++	84
DAS	2	1	Decimal adjust for subtraction	_	_	_	++++	94
XOR A	2	1	$(A) \leftarrow (AL) \ \forall \ (TL)$	_	_	_	+ + R –	52
XOR A,#d8	2	2	(A) ← (AL) ∀ d8	_	_	_	+ + R –	54
XOR A,dir	3	2	$(A) \leftarrow (AL) \ \forall \ (dir)$	_	_	_	+ + R –	55
XOR A,@EP	3	1	$(A) \leftarrow (AL) \ \forall \ (\ (EP) \)$	_	_	_	+ + R –	57
XOR A,@IX +off	4	2	$(A) \leftarrow (AL) \ \forall \ (\ (IX) + off)$	_	_	_	+ + R –	56
XOR A,Ri	3	1	$(A) \leftarrow (AL) \ \forall \ (Ri)$	_	_	_	+ + R -	58 to 5F
AND A	2	1	$(A) \leftarrow (AL) \wedge (TL)$	_	_	_	+ + R –	62
AND A,#d8	2	2	$(A) \leftarrow (AL) \land d8$	_	_	_	+ + R -	64
AND A,dir	3	2	$(A) \leftarrow (AL) \land (dir)$	_	_	_	+ + R –	65

(Continued)

(Continued)

Mnemonic	~	#	Operation	TL	TH	AH	NZVC	OP code
AND A,@EP	3	1	$(A) \leftarrow (AL) \land ((EP))$	_	-	-	+ + R –	67
AND A,@IX +off	4	2	$(A) \leftarrow (AL) \land ((IX) + off)$	_	_	_	+ + R -	66
AND A,Ri	3	1	$(A) \leftarrow (AL) \wedge (Ri)$	_	_	_	+ + R -	68 to 6F
OR A	2	1	$(A) \leftarrow (AL) \lor (TL)$	_	_	_	+ + R –	72
OR A,#d8	2	2	$(A) \leftarrow (AL) \lor d8$	_	_	_	+ + R -	74
OR A,dir	3	2	$(A) \leftarrow (AL) \lor (dir)$	_	_	_	+ + R -	75
OR A,@EP	3	1	$(A) \leftarrow (AL) \lor ((EP))$	_	_	_	+ + R -	77
OR A,@IX +off	4	2	$(A) \leftarrow (AL) \lor ((IX) + off)$	_	_	_	+ + R -	76
OR A,Ri	3	1	$(A) \leftarrow (AL) \lor (Ri)$	_	_	_	+ + R -	78 to 7F
CMP dir,#d8	5	3	(dir) – d8	_	_	_	++++	95
CMP @EP,#d8	4	2	((EP)) – d8	_	_	_	++++	97
CMP @IX +off,#d8	5	3	((IX) + off) - d8	_	_	_	++++	96
CMP Ri,#d8	4	2	(Ri) – d8	_	_	_	++++	98 to 9F
INCW SP	3	1	(SP) ← (SP) + 1	_	_	_		C1
DECW SP	3	1	(SP) ← (SP) – 1	_	_	_		D1

Table 4 Branch Instructions (17 instructions)

Mnemonic	~	#	Operation	TL	TH	AH	NZVC	OP code
BZ/BEQ rel	3	2	If $Z = 1$ then $PC \leftarrow PC + rel$	_	_	_		FD
BNZ/BNE rel	3	2	If $Z = 0$ then $PC \leftarrow PC + rel$	_	_	_		FC
BC/BLO rel	3	2	If $C = 1$ then $PC \leftarrow PC + rel$	_	_	_		F9
BNC/BHS rel	3	2	If $C = 0$ then $PC \leftarrow PC + rel$	_	_	_		F8
BN rel	3	2	If N = 1 then PC \leftarrow PC + rel	_	_	_		FB
BP rel	3	2	If N = 0 then PC \leftarrow PC + rel	_	_	_		FA
BLT rel	3	2	If $V \forall N = 1$ then $PC \leftarrow PC + rel$	_	_	_		FF
BGE rel	3	2	If $V \forall N = 0$ then $PC \leftarrow PC + rel$	_	_	_		FE
BBC dir: b,rel	5	3	If (dir: b) = 0 then $PC \leftarrow PC + rel$	_	_	_	-+	B0 to B7
BBS dir: b,rel	5	3	If (dir: b) = 1 then $PC \leftarrow PC + rel$	_	_	_	-+	B8 to BF
JMP @A	2	1	(PC) ← (A)	_	_	_		E0
JMP ext	3	3	(PC) ← ext	_	_	_		21
CALLV #vct	6	1	Vector call	_	_	_		E8 to EF
CALL ext	6	3	Subroutine call	_	_	_		31
XCHW A,PC	3	1	$(PC) \leftarrow (A), (A) \leftarrow (PC) + 1$	_	_	dΗ		F4
RET	4	1	Return from subrountine	_	_	_		20
RETI	6	1	Return form interrupt	_	_	_	Restore	30

Table 5 Other Instructions (9 instructions)

Mnemonic	~	#	Operation	TL	TH	AH	NZVC	OP code
PUSHW A	4	1		_	_	_		40
POPW A	4	1		_	_	dΗ		50
PUSHW IX	4	1		_	_	_		41
POPW IX	4	1		_	_	_		51
NOP	1	1		_	_	_		00
CLRC	1	1		_	_	_	R	81
SETC	1	1		_	_	_	S	91
CLRI	1	1		_	_	_		80
SETI	1	1		_	_	_		90

■ INSTRUCTION MAP

	NOIK	UCII		AP	I	I .	I .	l .	ı	I .			I	I .	I .	
ч	MOVW A,PC	MOVW A,SP	MOVW A,IX	MOVW A,EP	XCHW A,PC	XCHW A,SP	XCHW A,IX	XCHW A,EP	BNC	BC rel	BP rel	BN Tel	BNZ rel	BZ rel	BGE rel	BLT
Е	JMP @A	MOVW SP,A	MOVW IX,A	MOVW EP,A	MOVW A,#d16	MOVW SP,#d16	MOVW IX,#d16	MOVW EP,#d16	CALLV #0	CALLV #1	CALLV #2	CALLV #3	CALLV #4	CALLV #5	CALLV #6	CALLV #7
D	DECW A	DECW	DECW	DECW	MOVW ext,A	MOVW dir,A	MOVW @IX+d,A	MOVW @EP,A	DEC R0	DEC R1	DEC R2	DEC R3	DEC R4	DEC R5	DEC R6	DEC R7
C	INCW A	INCW SP	INCW IX	INCW	MOVW A,ext	MOVW A,dir	MOVW A,@IX +d	MOVW A,@EP	INC R0	INC R1	INC R2	INC R3	INC R4	INC R5	INC R6	INC R7
В	BBC dir: 0,rel	BBC dir: 1,rel	BBC dir: 2,rel	BBC dir: 3,rel	BBC dir: 4,rel	BBC dir: 5,rel	BBC dir: 6,rel	BBC dir: 7,rel	BBS dir: 0,rel	BBS dir: 1,rel	BBS dir: 2,rel	BBS dir: 3,rel	BBS dir: 4,rel	BBS dir: 5,rel	BBS dir: 6,rel	BBS dir: 7,rel
Α	CLRB dir: 0	CLRB dir: 1	CLRB dir: 2	CLRB dir: 3	CLRB dir: 4	CLRB dir: 5	CLRB dir: 6	CLRB dir: 7	SETB dir: 0	SETB dir: 1	SETB dir: 2	SETB dir: 3	SETB dir: 4	SETB dir: 5	SETB dir: 6	SETB dir: 7
6	SETI	SETC	MOV A,@A	MOVW A,@A	DAS	CMP dir,#d8	CMP @IX +d,#d8	CMP @EP;#d8	CMP R0,#d8	CMP R1,#d8	CMP R2,#d8	CMP R3,#d8	CMP R4,#d8	CMP R5,#d8	CMP R6,#d8	CMP R7,#d8
8	CLRI	CLRC	MOV @A,T	MOVW @A,T	DAA	MOV dir,#d8	MOV @1X+d,#d8	MOV @EP,#d8	MOV R0,#d8	MOV R1,#d8	MOV R2,#d8	MOV R3,#d8	MOV R4,#d8	MOV R5,#d8	MOV R6,#d8	MOV R7,#d8
7	MOVW A,PS	MOVW PS,A	OR A	ORW A	OR A,#d8	OR A,dir	OR A,@IX +d	OR A,@EP	OR A,R0	OR A,R1	OR A,R2	OR A,R3	OR A,R4	OR A,R5	OR A,R6	OR A,R7
9	MOV A,ext	MOV ext,A	AND A	ANDW	AND A,#d8	AND A,dir	AND A,@IX +d	AND A,@EP	AND A,R0	AND A,R1	AND A,R2	AND A,R3	AND A,R4	AND A,R5	AND A,R6	AND A,R7
5	POPW A	POPW IX	XOR A	XORW	XOR A,#d8	XOR A,dir	XOR A,@IX+d	XOR A,@EP	XOR A,R0	XOR A,R1	XOR A,R2	XOR A,R3	XOR A,R4	XOR A,R5	XOR A,R6	XOR A,R7
4	PUSHW A	PUSHW IX	XCH A, T	XCHW A, T		MOV dir,A	MOV @IX +d,A	MOV @EP,A	MOV R0,A	MOV R1,A	MOV R2,A	MOV R3,A	MOV R4,A	MOV R5,A	MOV R6,A	MOV R7,A
3	RETI	CALL addr16	SUBC	SUBCW	SUBC A,#d8	SUBC A,dir	SUBC A,@IX +d	SUBC A,@EP	SUBC A,R0	SUBC A,R1	SUBC A,R2	SUBC A,R3	SUBC A,R4	SUBC A,R5	SUBC A,R6	SUBC A,R7
2	RET	JMP addr16	ADDC A	ADDCW	ADDC A,#d8	ADDC A,dir	ADDC A, @IX +d	ADDC A,@EP	ADDC A,R0	ADDC A,R1	ADDC A,R2	ADDC A,R3	ADDC A,R4	ADDC A,R5	ADDC A,R6	ADDC A,R7
1	SWAP	DIVU A	CMP	CMPW	CMP A,#d8	CMP /	CMP A,@IX +d	CMP A,@EP	CMP A,R0	CMP A,R1	CMP A,R2	CMP A,R3	CMP A,R4	CMP A,R5	CMP A,R6	CMP A,R7
0	NOP	MULU A	ROLC A	RORC	MOV A,#d8	MOV A,dir	MOV A,@IX +d	MOV A,@EP	MOV A,R0	MOV A,R1	MOV A,R2	MOV A,R3	MOV A,R4	MOV A,R5	MOV A,R6	MOV A,R7
Н/ 	0	1	2	က	4	2	9	7	œ	6	∢	Δ.	ပ	۵	ш	ц

■ MASK OPTIONS

	Part number	MB89821/823	MB89P825	MB89PV820	
No.	Specifying procedure	ocedure Specify when ordering masking Set with EPROM programmer		Setting not possible (Fixed)	
1	Pull-up resistors P20 to P25, P30 to P33, P40 to P45	Selectable by pin	Can be set per pin	Without pull-up resistor	
2	Power-on reset With power-on reset Without power-on reset	Selectable	Can be set	With power-on reset	
3	Oscillation stabilization time selection (Fc = 5 MHz) ¹¹ Approx. 2 ¹⁷ /Fc (Approx. 26.2 ms) Approx. 2 ¹³ /Fc (Approx. 1.64 ms)	Selectable	Can be set	Oscillation stabilization time Approx. 2 ¹⁷ /Fc (Approx. 26.2 ms)	
4	Reset pin output With reset output Without reset output	Selectable	Can be set	With reset output	
5	Segment output switching 50 segments: No port selection 49 segments: Selection of P17 48 segments: Selection of P17 to P16 46 segments: Selection of P17 to P14 42 segments: Selection of P17 to P10 34 segments: Selection of P17 to P10 and P07 to P00	Selectable*2	Can be set*3	Can be set*3	

^{*1:} The oscillation settling time is generated by dividing the oscillation clock frequency. Since the oscillation period is not stable immediately after oscillation has been started, therefore, the oscillation settling time in the above list should be regarded as a reference.

Ports are set by the register setting of the segment output selection register of LCD controller.

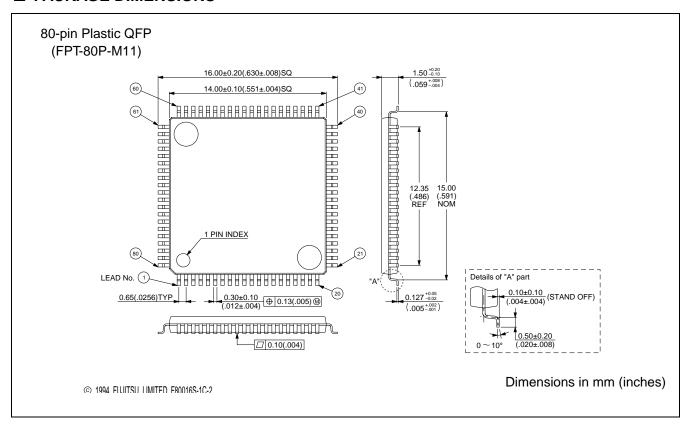
■ ORDERING INFORMATION

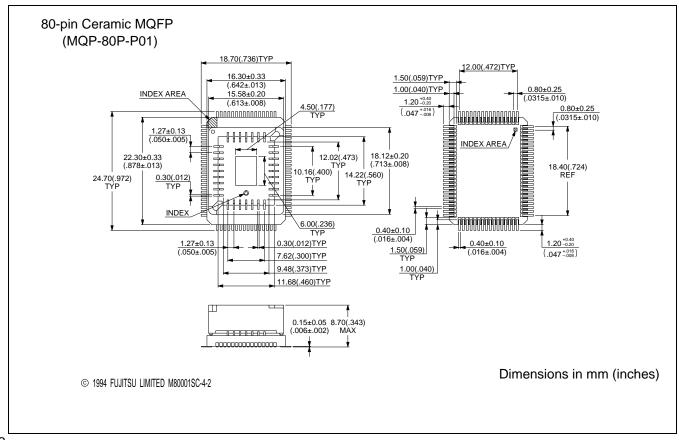
Part number	Package	Remarks
MB89821PFM MB89823PFM MB89P825PFM	80-pin Plastic QFP (FPT-80P-M11)	
MB89PV820CF	80-pin Ceramic MQFP (MQP-80C-P01)	

^{*2:} Port selection must be same setting of the segment output selection register of LCD controller.

^{*3:} Note that, when ports are set, the input voltage value for the port pins are different from those for mask ROM products.

■ PACKAGE DIMENSIONS





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